503303844 05/12/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3350462

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Pin-Hong Chen	05/06/2015
Kuo-Chih Lai	05/06/2015
Chia Chang Hsu	05/06/2015
Chun-Chieh Chiu	05/06/2015
Li-Han Chen	05/06/2015
Shu Min Huang	05/06/2015
Min-Chuan Tsai	05/06/2015
Hsin-Fu Huang	05/06/2015
Chi-Mao Hsu	05/06/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14710583

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2480USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/

PATENT 503303844 REEL: 035622 FRAME: 0732

DATE SIGNED:	05/12/2015
Total Attachments: 18	
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PATENT REEL: 035622 FRAME: 0733

Title of Invention: SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	file	d on	, or
☐ PCT international application	number	1	iled on	
The above-identified application was	made or authorized to	be made by m	e.	
I believe that I am the original inventapplication.	or or an original joint ir	nventor of a clair	med invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	l false statement made isonment of not more t	e in this declarat han five (5) yea	ion is punishable rs, or both.	
In consideration of the payment by	UNITED MICROEL CORP.	ECTRONICS	having a postal a	ddress of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-C	hu City 300, Taiwa	ın, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One D d valuable considerati	ollar (\$ 1.00), thon.	ne receipt of which is h	nereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica- invention by the above application or substitutes, or extensions thereof, an	nd to any and all impro tion and, in and to, all any continuations, co	vements which Letters Patent to ntinuation-in-pa	are disclosed in the be obtained for said rt, divisions, renewals.	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or on this assignment;	encumbrance h	as been or will be mad	le or
I further covenant that ASSIGNEE wand documents relating to said invented known and accessible to I and will terelated thereto and will promptly executed.	tion and said Letters F stify as to the same in	Patent and legal any interference	equivalents as may be, litigation proceeding	е
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable to	and said Letter carry out the p	s Patent and said roposes thereof.	e of signing)
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 1 of 18

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Pin-Hong Chen	Date:	MAY 0 6 2015
Signature:	1977-Hong Ohen	,	

Page 2 of 18

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(referred to as "ASSIGNEE"below) to acknowledged, and for other good and I hereby sell, assign and transfer to A	d valuable considerati	on.	·	•
the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all impro tion and, in and to, all rany continuations, co	vements which Letters Patent t ntinuation-in-pa	are disclosed in o be obtained fo rt. divisions, ren	the or said newals.
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I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters F stify as to the same in	atent and legal any interferenc	equivalents as e, litigation proc	mav be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable to	and said Letter carry out the p	rs Patent and sa	iid f. _(Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent) s form. Use this form fo	, including nami or <u>each addition</u>	ng the entire al inventor.	

Page 3 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

LEGAL NAI	ME OF INVENT	OR(ASSIGNOR)					
Inventor:	Kuo-Chih La	ai	Date:	MAY	0 6	2015	
Signature:	Lai-	kus-dih					

Page 4 of 18

Title of Invention: SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

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The above-identified application was	made or authoriz	ed to be made b	y me.		
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	id to any and all in ion and, in and to any continuations	nprovements wh , all Letters Pate s, continuation-ir	nich are ent to be n-part. d	disclosed in the e obtained for said livisions, renewals	EE
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreemen this assignment;	t or encumbrand	ce has t	peen or will be made	or
I further covenant that ASSIGNEE wi and documents relating to said invent known and accessible to I and will test related thereto and will promptly exec	tion and said Lette stify as to the sam	ers Patent and le le in any interfer	egal equence, lit	uivalents as may be	ts
representatives any and all papers, ir maintain, issue and enforce said appi equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	lication, said inver cessary or desirat	ntion and said Le	etters P he prop	atent and said oses thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	n/SB/14 or equival form. Use this fo	ent), including n rm for <u>each add</u>	aming t itional ir	the entire	

Page 5 of 18

LEGAL NA	WE OF INVENTORIAS	Sicilory			
Inventor:	Chia Chang Hsu		Date:	MAY 0 6 2015	
Signature:	Chra	Chang	Hzn		## ***********************************

Page 6 of 18

Title of Invention:

SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

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I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat rany continuations, continuation-i	hich are disclosed in ent to be obtained fo n-part, divisions, ren	the or said ewals.
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or will b	e made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and I stify as to the same in any interfe	legal equivalents as rence, litigation proc	mav be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out t	etters Patent and sa	iid f. _(Date of signing) _
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including r s form. Use this form for <u>each ado</u>	naming the entire ditional inventor.	

Page 7 of 18

PATENT REEL: 035622 FRAME: 0740

LEGAL NAI	ME OF INVENTOR(ASSIGN	NOR)			
Inventor:	Chun-Chieh Chiu		Date:	MAY 0 6 2015	
Signature:	Chun-Chieh	Chiu	_		

Page 8 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

Title of Invention:

SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed	on	, or
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The above-identified application was	made or authorized to	be made by me.		
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I hereby covenant that no assignment entered into which would conflict with		encumbrance has	been or will b	e made or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable to	and said Letters carry out the pro	Patent and sai	d (Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 9 of 18

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Li-Han Chen	Date:	MAY 0 6 2015	
Signature:	Li-Han Chen			

Page 10 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

Title of Invention:

SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

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Page 11 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Shu Min Huang	Date:	MAY 0 6 2015	
Signature:	. Shu Min Huang			
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Page 12 of 18

Title of Invention:

SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

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Page 13 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

LEGAL NAM	WE OF INVENTOR(ASSIGNOR)			
Inventor:	Min-Chuan Tsai	Date:	MAY 0 6 2015	
Signature:	Min Chuan TSAT			

Page 14 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

Title of Invention:

SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG

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Page 15 of 18

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LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Hsin-Fu Huang	Date:	MAY 0 6 2015	
Signature:	Hisin Fu Huang			

Page 16 of 18

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Page 17 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

LEGAL NAI	WE OF INVENTOR(ASSIGNOR)				
Inventor:	Chi-Mao Hsu	Date:	MAY	0 6 2015	
Signature:	Chi-Mao Hsu	•	-		

Page 18 of 18

NPO#NAU-P2480-USA:0 CUST#UMCD-2015-0060

RECORDED: 05/12/2015

F#NPO-P0002E-US1201 DSC0-104U003216

PATENT REEL: 035622 FRAME: 0751